

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLS115B0LD	**Issued**	16. July 2019
MA#	MA005350788		
Package	PG-TSON-10-2	**Weight***	31.75 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.123	3.54	3.54	35367	35367
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		104	
	non noble metal	zinc	7440-66-6	0.013	0.04		418	
	non noble metal	iron	7439-89-6	0.265	0.84		8357	
	non noble metal	copper	7440-50-8	10.773	33.93	34.82	339324	348203
wire	non noble metal	copper	7440-50-8	0.032	0.10	0.10	1009	1009
encapsulation	organic material	carbon black	1333-86-4	0.037	0.12		1175	
	plastics	epoxy resin	-	1.922	6.05		60528	
	inorganic material	silicondioxide	60676-86-0	16.698	52.59	58.76	525949	587652
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11657	11657
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2024	2024
glue	plastics	epoxy resin	-	0.112	0.35		3522	
	noble metal	silver	7440-22-4	0.335	1.06	1.41	10566	14088
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com